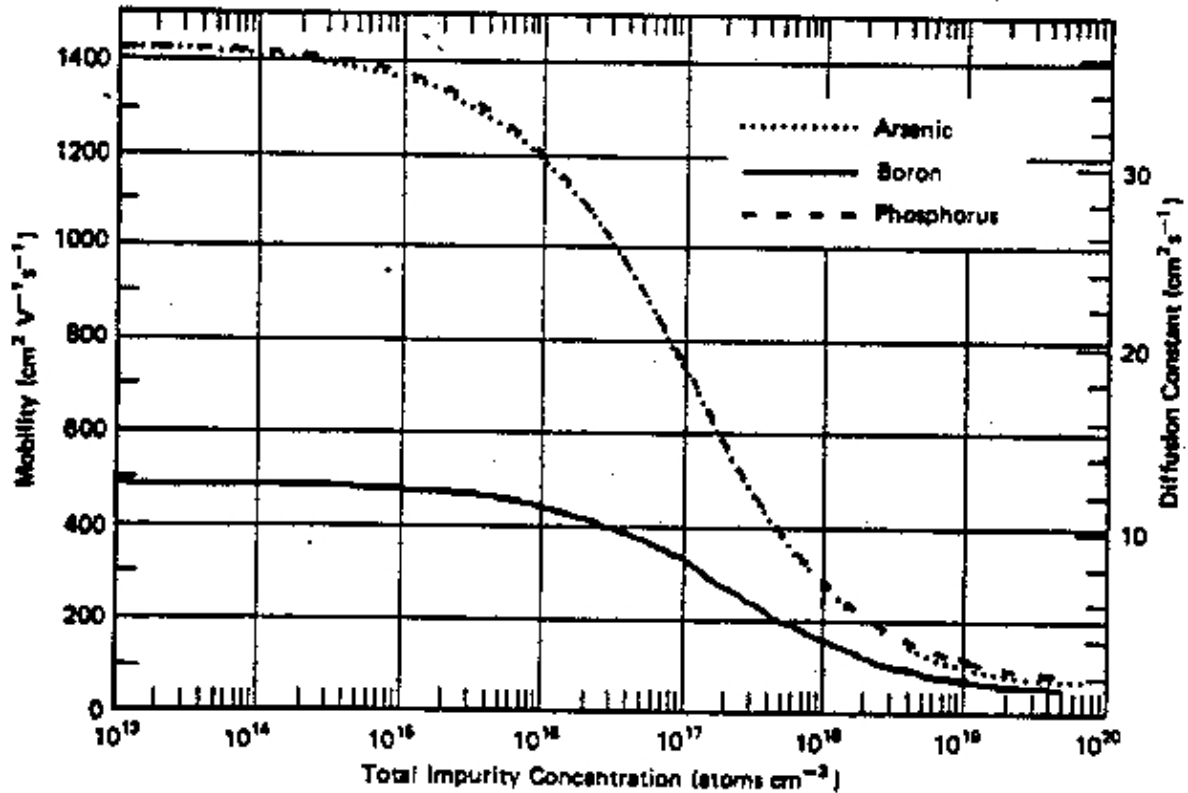


EECS 130 Midterm Exam #1 : N. Cheung, Spring '93

GENERAL INFORMATION



$q = 1.6 \times 10^{-19}$
 $\epsilon_s = 1.036 \times 10^{-12} \text{ F/cm}$ for Si
 n_i of Si = $1.45 \times 10^{10} \text{ cm}^{-3}$ at 300K
 E_g of Si = 1.12 eV at 300K
 Electron Affinity of Si = 4.05 eV
 $D/\mu = kT/q = 0.0259$ volts at 300K
 $n_i^2 = N_c N_v \exp[-E_g/kT]$

Electric potential of semiconductor:

$$\phi = (E_f - E_i) / q$$

$$n = n_i \cdot \exp(q\phi/kT)$$

$$p = n_i \cdot \exp(-q\phi/kT)$$

Step pn junction depletion width:

$$x_d = [2\epsilon_s/q (\phi - V_a) (1/N_a + 1/N_d)]^{1/2}$$

Poisson's Equation:

$$d^2 \phi / dx^2 = -q/\epsilon_s \{ p - n + N_d - N_a \}$$

Small-signal capacitance/unit area: $C = \epsilon_s / x_d$

Sheet resistance $R_s = 1 / (Nq\mu)$

Problem 1 (20 points total)

(a) (8 points) Energy gaps and intrinsic carrier concentration at 300K are given for the following three semiconductors:

- Si: $E_g = 1.124 \text{ eV}$, $n_i = 1.45 \times 10^{10} / \text{cm}^3$
 Ge: $E_g = 0.66 \text{ eV}$, $n_i = 2.4 \times 10^{13} / \text{cm}^3$
 GaAs: $E_g = 1.424 \text{ eV}$, $n_i = 1.79 \times 10^6 / \text{cm}^3$

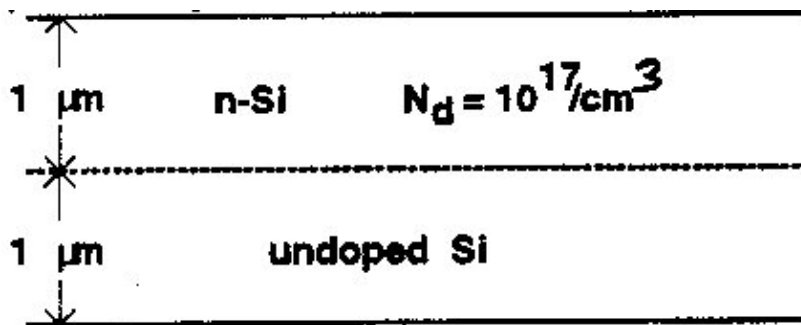
The three semiconductors are doped such that at 300K, $N_a - N_d = 1 \times 10^{15} / \text{cm}^3$. Which semiconductor has the most sensitive change to temperature for its minority carrier? Explain.

(b) (12 points) A piece of p-type Si has an acceptor concentration profile: $N_a(x) = N_0 \exp(-Kx)$, where x is the position for the region of interest. N_0 and K are constants.

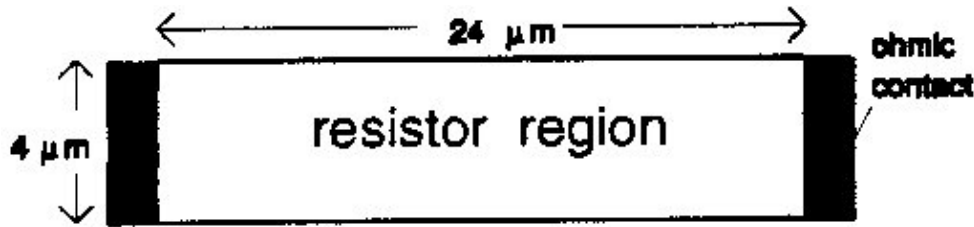
- (i) Find an expression for the hole diffusion current density J_p diffusion(x) at thermal equilibrium.
- (ii) Find an expression for the electron diffusion current density J_n diffusion(x) at thermal equilibrium.
- (iii) Find an expression for the electric field $E(x)$ at thermal equilibrium.
- (iv) What are the reasons that J_p diffusion (x) is not equal to J_n diffusion (x)?

Problem 2 (20 points total)

A piece of Si has a thickness of 2 μm . The top 1 μm is doped to an n-type with $N_d = 10^{17} / \text{cm}^3$. The bottom 1 μm is undoped.



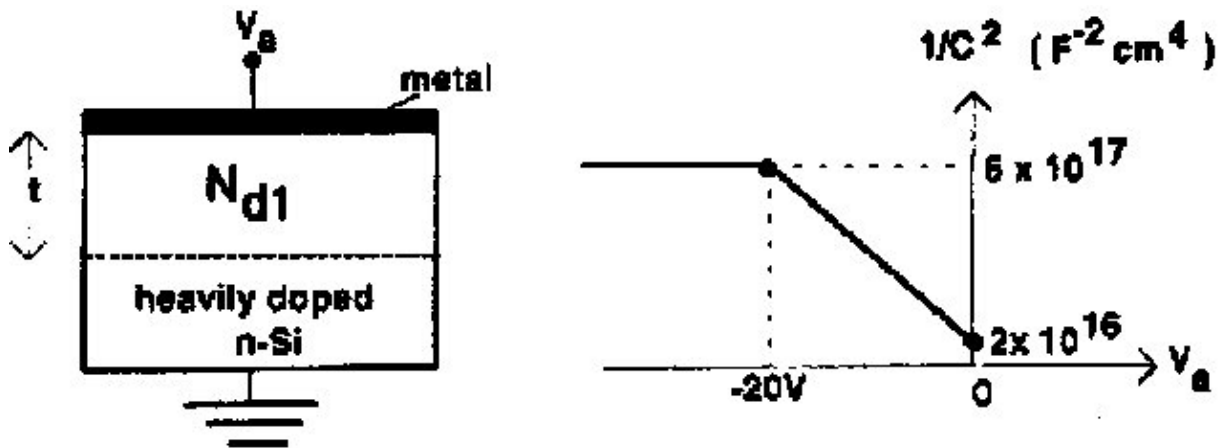
- (a) (7 points) Calculate the sheet resistance R_s at 300K.
- (b) (3 points) A resistor pattern is laid out for an integrated circuit as shown in the sketch below. Find the resistance of this IC resistor.



(c) (10 points) A uniform concentration of boron ($= 10^{17}/\text{cm}^3$) then added to the top $1\ \mu\text{m}$ region. Calculate the new sheet resistance.

Problem 3 (30 points total)

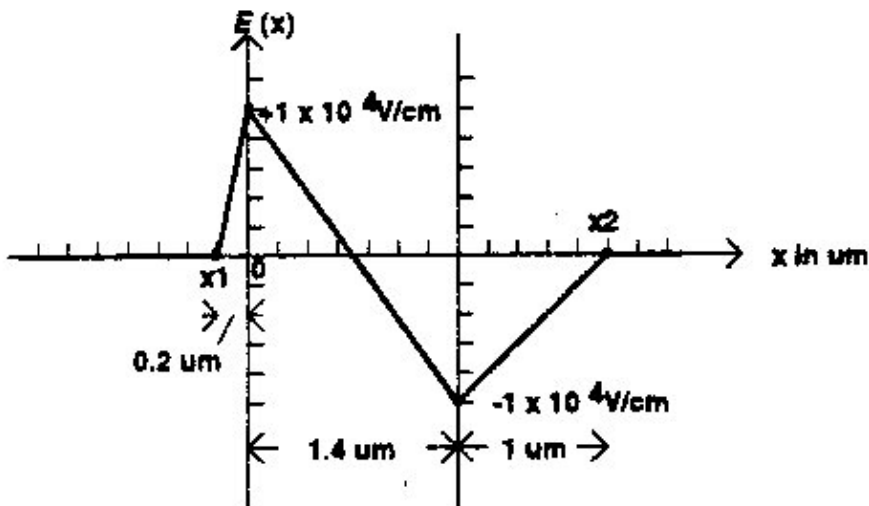
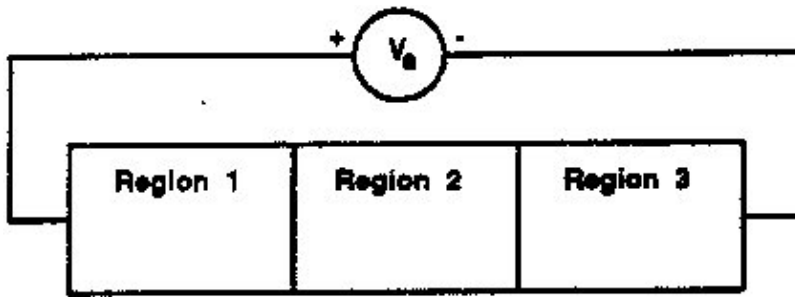
A Schottky rectifying contact is made using a thin uniformly doped Si layer (concentration = N_{d1}) on top of a very heavily doped Si substrate. Small-signal capacitance measurements were made and the $1/C^2 - V_a$ plot is shown below.



- (a) (6 points) Find the doping concentration N_{d1} .
- (b) (6 points) Find the thickness of the N_{d1} layer.
- (c) (10 points) Find the Schottky barrier height of the contact ϕ_B . [Hint: you may want to draw a rough sketch of the energy band diagram to identify the various components for ϕ_B]
- (d) (8 points) If avalanche breakdown will occur at an electric field of $7 \times 10^4\ \text{V/cm}$, find the required V_a . Show the procedures which give you the answer.

Problem 4 (30 points total)

A piece of Si has three regions of different doping. At a certain bias V_a , the electric field profile is shown below.



(a) (12 points) Answer the following questions:

(i) Region 1 is n-type / p-type (circle one) and has a doping concentration of _____.

(ii) Region 2 is n-type / p-type (circle one) and has a doping concentration of _____.

(iii) Region 3 is n-type / p-type (circle one) and has a doping concentration of _____.

(b) (8 points) Find the potential difference between position x_1 and x_2 (i.e., $\phi(x_1) - \phi(x_2)$).

(c) (10 points) Sketch the corresponding energy band diagram. Show E_c , E_v and the Fermi levels in the quasi-neutral regions of Region 1 and Region 3.